TK695 - CyberOptics SE300 Solder Paste Inspection (2004)

Model: SE300 Solder Paste Inspection

SKU:

Year: 2004



Description:

CyberOptics SE300 (2004) Solder Paste Inspection

Brand: Cyberoptics
Model: SE300
Description: Solder Paste Inspection
Serial: 10239
Year: 2004

Details:

- MicroPad Sensor
- Mechanical board stop
- Auto-width adjust conveyor
- Max pad size: 0.197" x 0.394"
- Paste height range: 2-14mils
- Height resolution: 0.005mils
- Weight: 860 kg (1900 lbs.)
- Process Insight SPC software

- Max PCB width: 20” x 20”
- Max inspection area: 20” x 19.5”
- Board Thickness: 0.5 to 5 mm (0.02 to 0.2 in.)
- Board Edge Clearance: Top: 2.5 mm (0.10 in.)

Bottom: 3 mm (0.12 in.)

Underside Component Clearance: 25.4 mm (1 in.)

- GC-PowerPlace Gerber and ODB++ file conversion software for off-line programming
- NIST-traceable measurement certification standard certified for height, area and volume
- Measurement types: Height, Area, Volume, Registration, Bridge Detection

